

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination	
		09/911,069	PERRY ET AL.	
Examiner John L. Goff		Art Unit 1733	Page 1 of 1	

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages
	U	IBM Technical Disclosure Bulletin - "Solder Plated Resin Ball" Published May 1995
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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